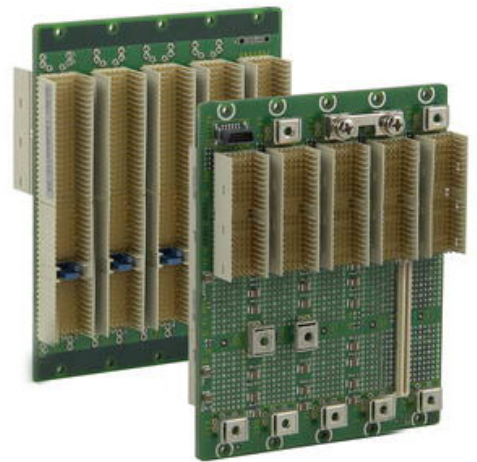


# BP3106

## *3U CompactPCI<sup>®</sup> PlusIO backplane*

- **Conforms to latest PICMG**
- **10-layer, high-performance, low noise stripline design**
- **Custom configurations available**
- **PICMG 2.0 R3.0 CompactPCI specification compliant**
- **PICMG 2.1 R1.0 cPCI Hot Swap specification compliant**
- **Standard versions 5 slots**
- **V(I/O) adjustable to +3.3 V or +5 V**
- **Digital GND can be connected to isolated from chassis GND by means of screws**



**Embedded  
Solutions**

**SKYTOP ELECTRONICS Ltd**

# Technical Data

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## Electrical Specifications

- Backplane Connectors: IEC 1076-4-101, 2 mm press-fit pin and socket
- Connector Pitch: 4 HP (0.8") spacing
- Insulation Resistance: acc. IEC 512-5
- Transmission Rate:
  - 132 Mbytes/s (peak) for 32-bit transmissions @ 33 MHz
  - 264 Mbytes/s (peak) for 32-bit transmissions @ 66 MHz
- Characteristic of Impedance: 65 ohms  $\pm 10\%$

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## Mechanical Specifications

- Dimensions: conforming to CompactPCI<sup>®</sup> specification for 3U boards
- Weight: 200g
- Backplane Material: FR4

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## Environmental Specifications

- Temperature range (operation): -40..+85°C
- Temperature range (storage): -40..+85°C
- Relative humidity (operation): max. 95% non-condensing
- Relative humidity (storage): max. 95% non-condensing
- Altitude: -300m to + 3,000m
- Shock: 15g/11ms
- Bump: 10g/16ms
- Vibration (sinusoidal): 2g/10..200Hz
- Conformal coating on request

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## MTBF

500 000 h @ 40°C (derived from MIL-HDBK-217F)

# *Contact Information*

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## **Hong Kong**

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